

P-Ch 30V Fast Switching MOSFETs

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary



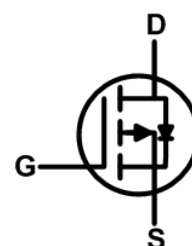
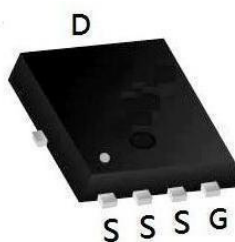
| BVDSS | RDS(on) | ID |
|-------|---------|------|
| -30V | 6.5mΩ | -65A |

Description

The XR70P03D is the high cell density trenched P-ch MOSFETs, which provide excellent RDS(on) and gate charge for most of the synchronous buck converter applications.

The XR70P03D meet the RoHS and Gree Product requirement 100% EAS guaranteed with full function reliability approved.

PDFN3333-8L Pin Configuration



Absolute Maximum Ratings

| Parameter | | Symbol | Value | Unit |
|--|-------------------|----------------|------------|------|
| Drain-Source Voltage | | V_{DS} | -30 | V |
| Gate-Source Voltage | | V_{GS} | ±20 | V |
| Continuous Drain Current@-10V ¹ | $T_C=25^{\circ}C$ | I_D | -65 | A |
| | $T_C=75^{\circ}C$ | | -35 | |
| Pulsed Drain Current ² | | I_{DM} | -175 | A |
| Single Pulse Avalanche Energy ³ | | EAS | 31 | mJ |
| Avalanche Current | | I_{AS} | -70 | A |
| Total Power Dissipation ⁴ | $T_C=25^{\circ}C$ | P_D | 31.2 | W |
| Operating Junction and Storage Temperature Range | | T_J, T_{STG} | -55 to+150 | °C |

Thermal Characteristics

| Parameter | Symbol | Value | Unit |
|--|-----------------|-------|------|
| Thermal Resistance from Junction-to-Ambient ¹ | $R_{\theta JA}$ | 61 | °C/W |
| Thermal Resistance from Junction-to-Case ¹ | $R_{\theta JC}$ | 4 | °C/W |

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Electrical Characteristics $T_c = 25^\circ\text{C}$, unless otherwise noted

| Parameter | | Symbol | Test Conditions | Min. | Typ. | Max. | Unit |
|--|----------------------|----------------------|--|------|------|------|------|
| Static Characteristics | | | | | | | |
| Drain-Source Breakdown Voltage | | V _{(BR)DSS} | V _{GS} = 0V, I _D = -250μA | -30 | - | - | V |
| Gate-body Leakage current | | I _{GSS} | V _{DS} = 0V, V _{GS} = ±20V | - | - | ±100 | nA |
| Zero Gate Voltage Drain Current | T _J =25°C | I _{DSS} | V _{DS} = -24V, V _{GS} = 0V | - | - | -1 | μA |
| | T _J =55°C | | | - | - | -5 | |
| Gate-Threshold Voltage | | V _{GS(th)} | V _{DS} = V _{GS} , I _D = -250μA | -1.0 | -1.6 | -2.5 | V |
| Drain-Source On-Resistance ² | | R _{DS(on)} | V _{GS} = -10V, I _D = -12A | - | 6.5 | 9.3 | mΩ |
| | | | V _{GS} = -4.5V, I _D = -8A | - | 9.5 | 14.5 | |
| Forward Transconductance | | g _{fs} | V _{DS} = -5V, I _D = -20A | - | 28 | - | S |
| Dynamic Characteristics | | | | | | | |
| Input Capacitance | | C _{iss} | V _{DS} = -15V, V _{GS} =0V, f =1MHz | - | 4320 | - | pF |
| Output Capacitance | | C _{oss} | | - | 529 | - | |
| Reverse Transfer Capacitance | | C _{rss} | | - | 487 | - | |
| Switching Characteristics | | | | | | | |
| Gate Resistance | | R _g | V _{DS} = 0V, V _{GS} = 0V, f=1.0MHz | - | 4.0 | - | Ω |
| Total Gate Charge | | Q _g | V _{GS} = -10V, V _{DS} = -15V, I _D = -15A | - | 45 | - | nC |
| Gate-Source Charge | | Q _{gs} | | - | 8.5 | - | |
| Gate-Drain Charge | | Q _{gd} | | - | 12.8 | - | |
| Turn-On Delay Time | | t _{d(on)} | V _{GS} = -10V, V _{DD} = -15V, R _G = 2.5Ω, I _D = -15A | - | 18.9 | - | nS |
| Rise Time | | t _r | | - | 15.7 | - | |
| Turn-Off Delay Time | | t _{d(off)} | | - | 64.8 | - | |
| Fall Time | | t _f | | - | 36.5 | - | |
| Drain-Source Body Diode Characteristics | | | | | | | |
| Diode Forward Voltage ² | | V _{SD} | I _S = -1A, V _{GS} = 0V | - | - | -1 | V |
| Continuous Source Current ^{1,5} | | I _S | V _G =V _D =0V , Force Current | - | - | -65 | A |

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{DD} = -25V, V_{GS} = -10V, L = 0.1mH, I_{AS} = -25A$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

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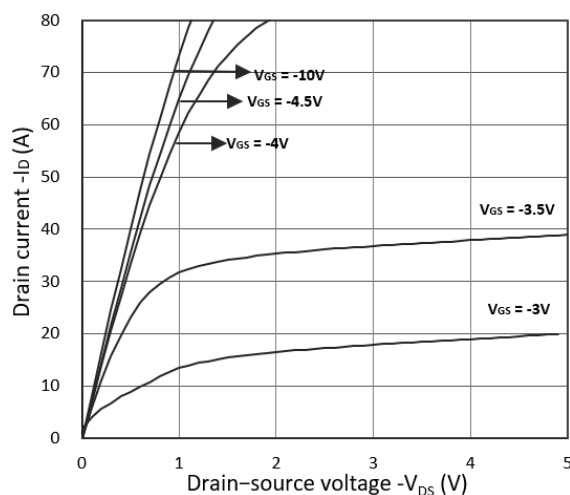


Figure 1. Output Characteristics

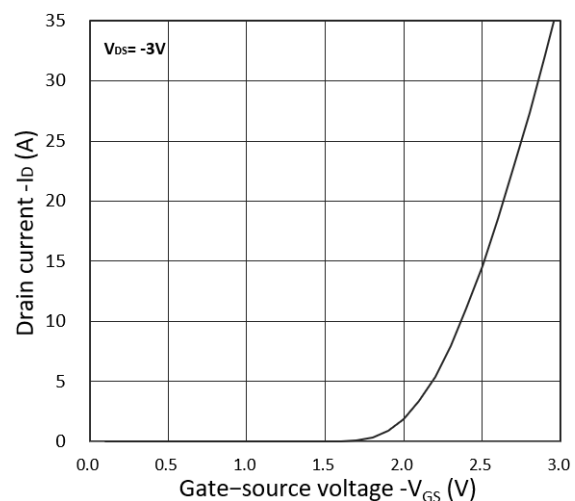


Figure 2. Transfer Characteristics

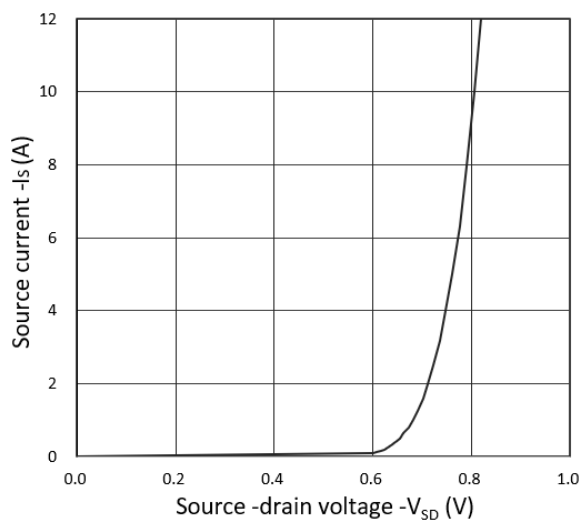


Figure 3. Forward Characteristics of Reverse

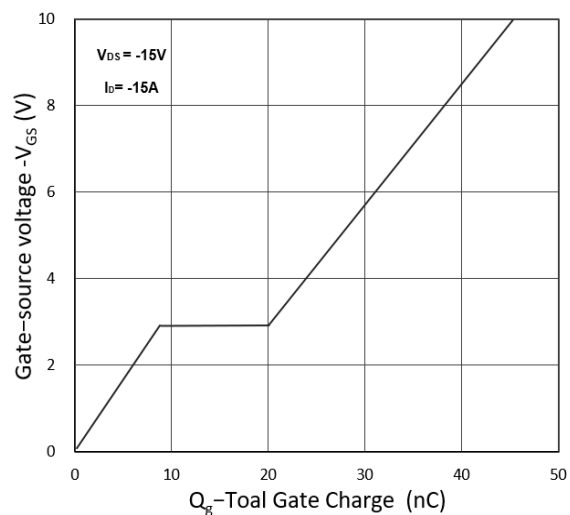


Figure 4. Gate Charge Characteristics

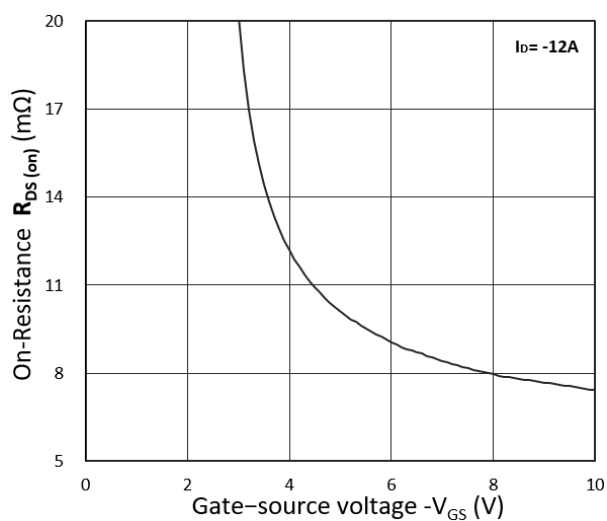


Figure 5. $R_{DS(on)}$ vs. V_{GS}

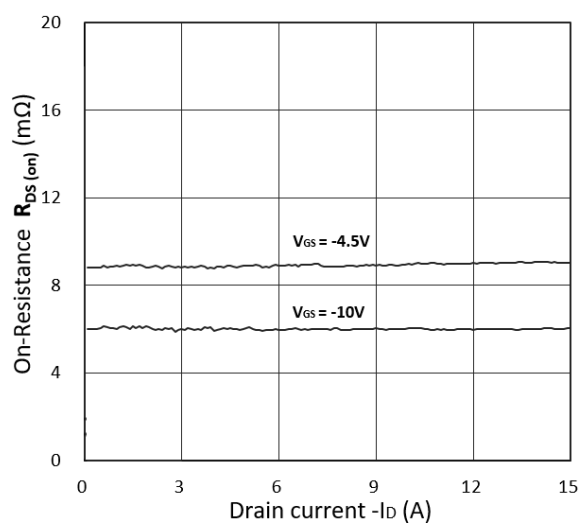


Figure 6. $R_{DS(on)}$ vs. I_D

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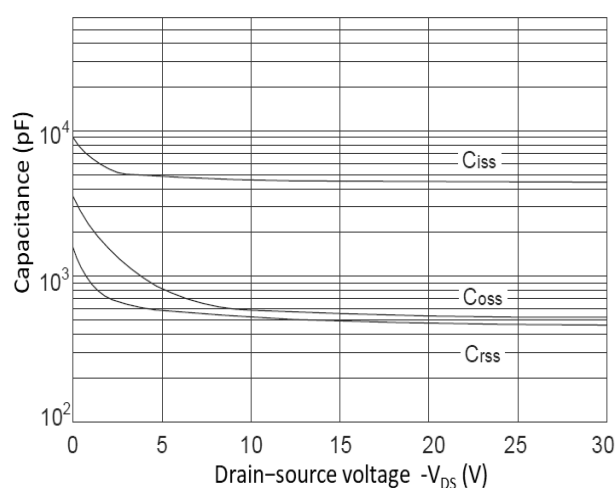


Figure 7. Capacitance Characteristics

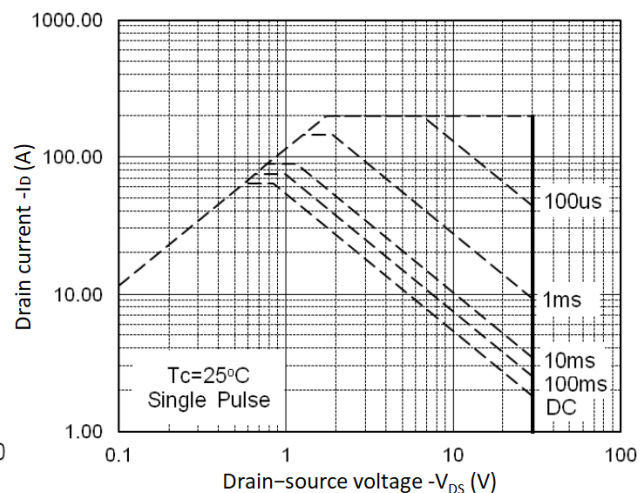


Figure 8. Safe Operating Area

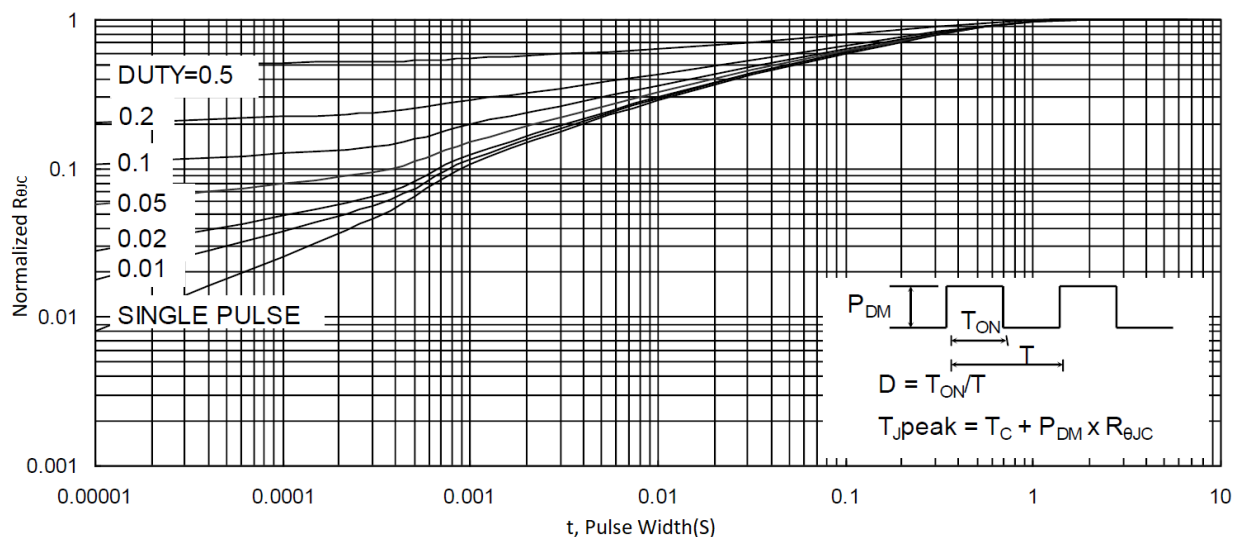


Figure 9. Normalized Maximum Transient Thermal Impedance

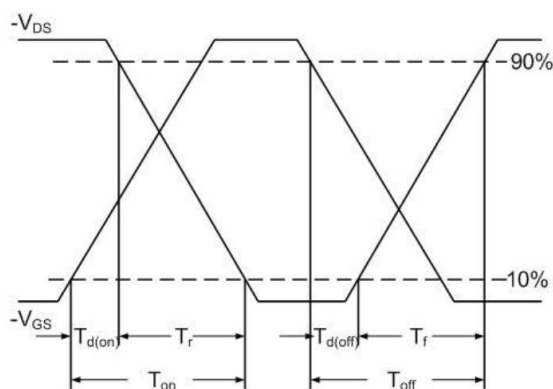


Figure 10. Switching Time Waveform

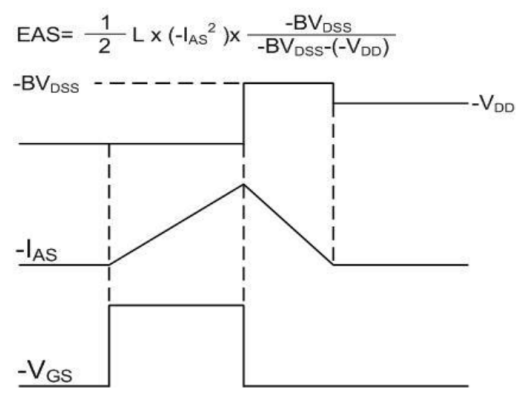
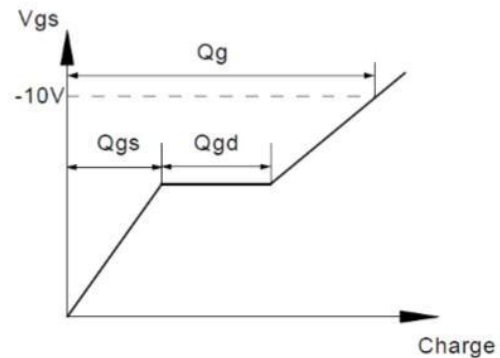
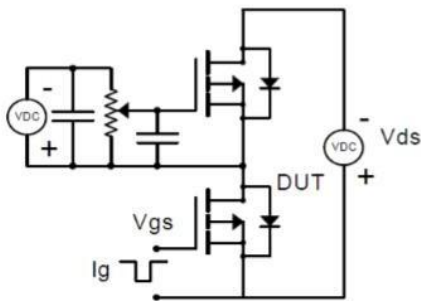


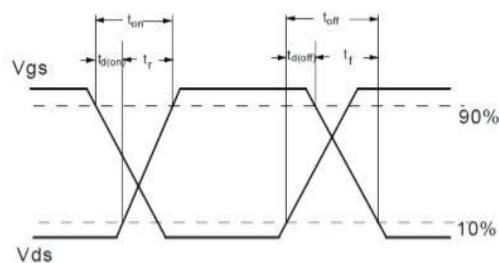
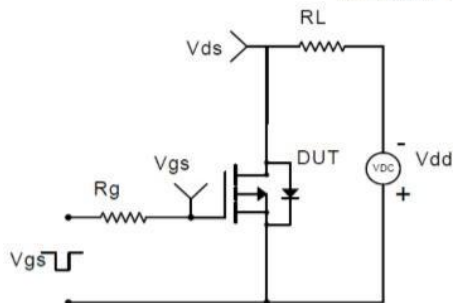
Figure 11. Unclamped Inductive Switching
Waveform

Test Circuit

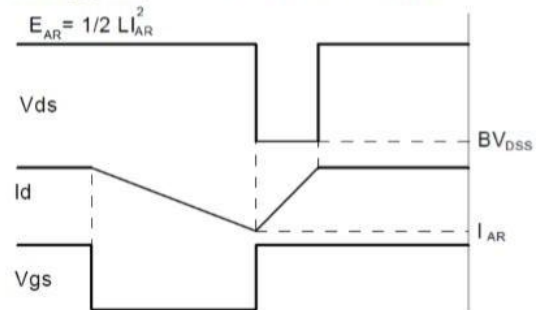
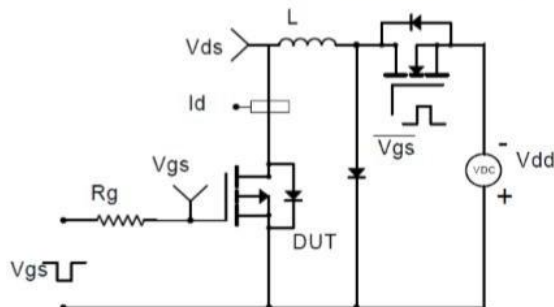
Gate Charge Test Circuit & Waveform



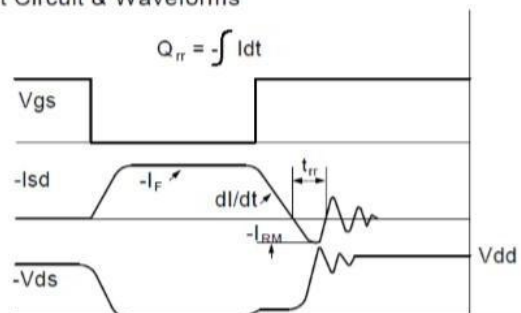
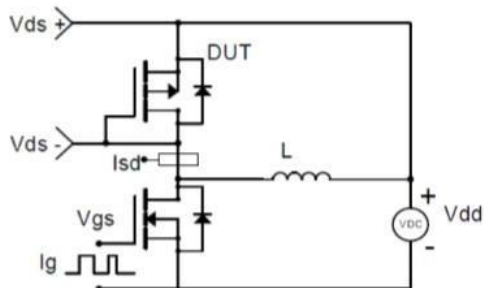
Resistive Switching Test Circuit & Waveforms



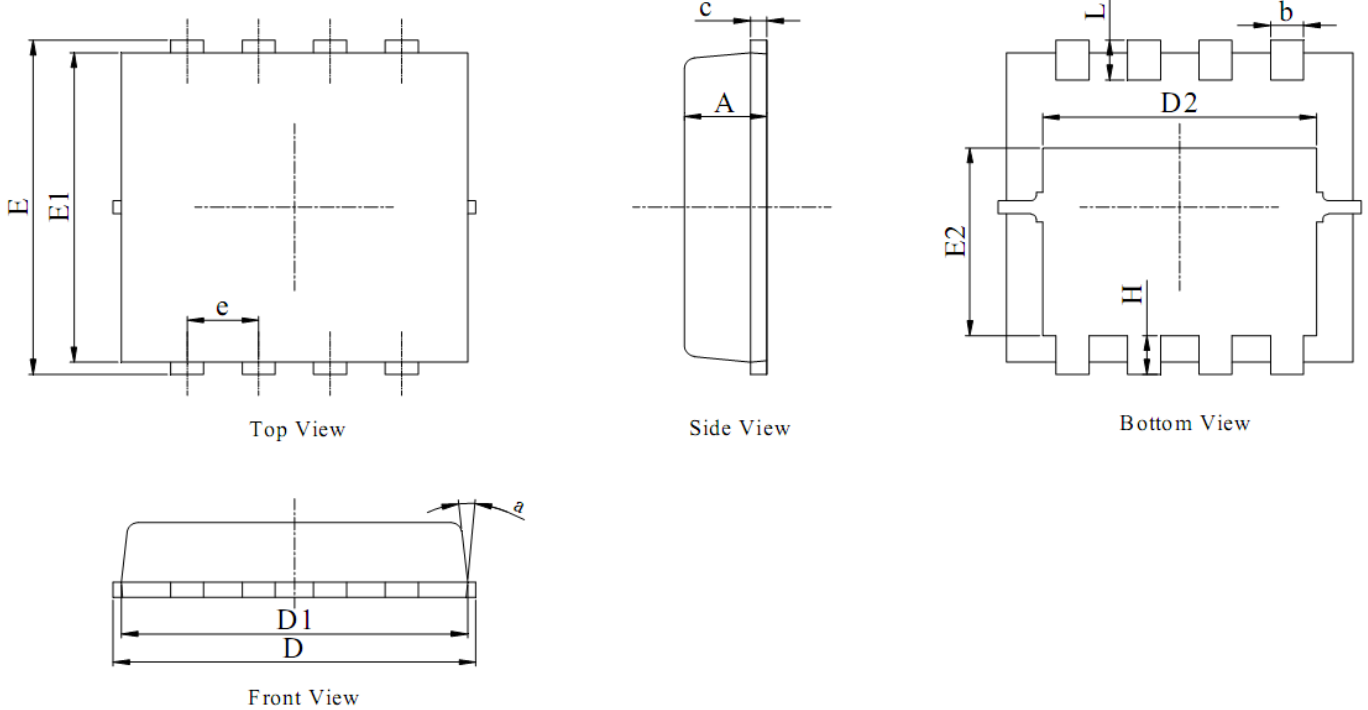
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



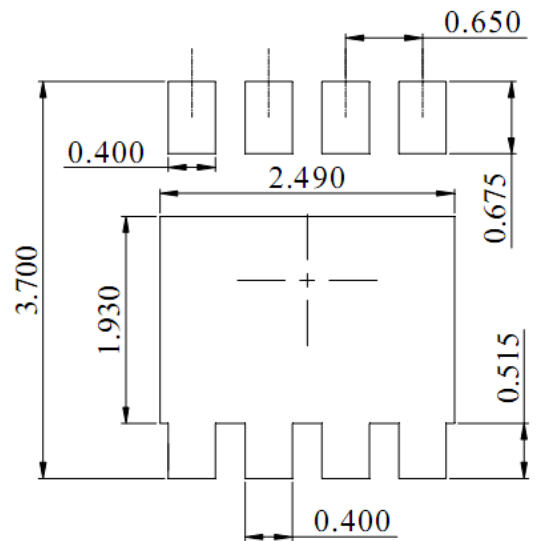
Package Mechanical Data-PDFN3333-8L-Single



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
2. ALL DIMNESIONS IN MILLIMETER (ANNGLE IN DEGREE).
3. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

| DIM. | MILLIMETER | | |
|------|------------|------|------|
| | MIN. | NOM. | MAX. |
| A | 0.70 | 0.75 | 0.80 |
| b | 0.25 | 0.30 | 0.35 |
| c | 0.10 | 0.20 | 0.25 |
| D | 3.00 | 3.15 | 3.25 |
| D1 | 2.95 | 3.05 | 3.15 |
| D2 | 2.39 | 2.49 | 2.59 |
| E | 3.20 | 3.30 | 3.40 |
| E1 | 2.95 | 3.05 | 3.15 |
| E2 | 1.70 | 1.80 | 1.90 |
| e | 0.65 BSC | | |
| H | 0.30 | 0.40 | 0.50 |
| L | 0.25 | 0.40 | 0.50 |
| a | --- | --- | 15° |



DIMENSIONS:MILLIMETERS